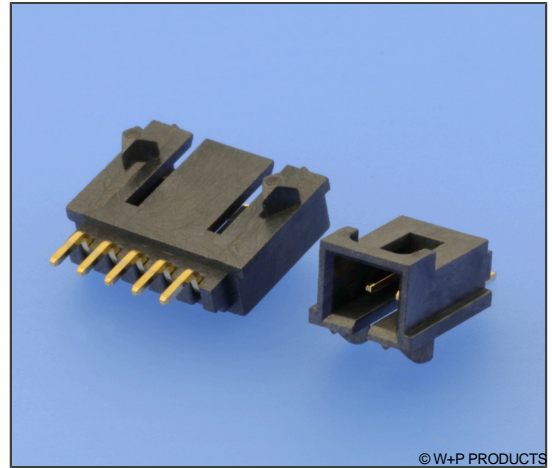


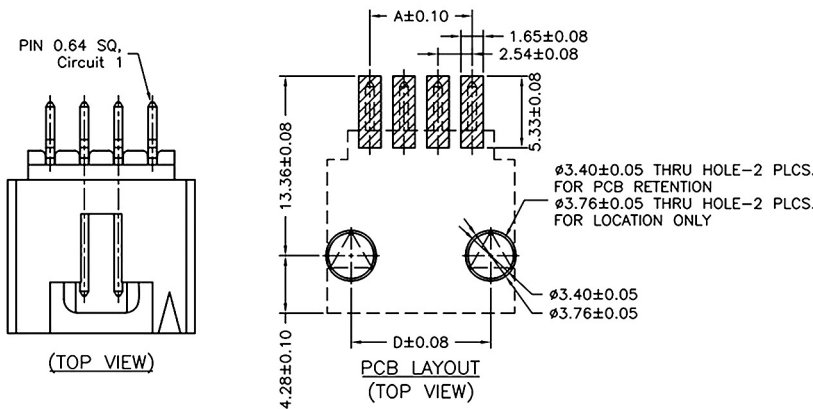
Technische Daten / Technical Data

Isolierkörper <i>Insulator</i>	Thermoplast, nach UL94 V-0 <i>Thermoplastic, rated UL94 V-0</i>
Kontaktmaterial <i>Contact Material</i>	Vierkantstift 0,64mm, Kupferlegierung <i>0.64mm square pin, copper alloy</i>
Durchgangswiderstand <i>Contact Resistance</i>	< 20 mΩ <i>< 20 mΩ</i>
Isolationswiderstand <i>Insulation Resistance</i>	> 1000 MΩ <i>> 1000 MΩ</i>
Spannungsfestigkeit <i>Test Voltage</i>	1500 V AC <i>1500 V AC</i>
Nennspannung <i>Voltage Rating</i>	250 V AC <i>250 V AC</i>
Nennstrom <i>Current Rating</i>	3 A <i>3 A</i>
Temperaturbereich <i>Temperature Range</i>	-25 °C ... +85 °C <i>-25 °C ... +85 °C</i>
Verarbeitung <i>Processing</i>	Reflow-Lötverfahren <i>Reflow soldering</i>

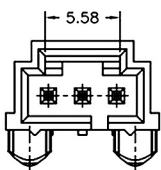
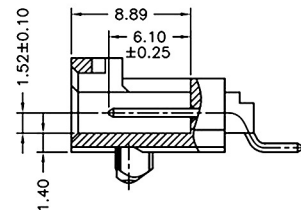
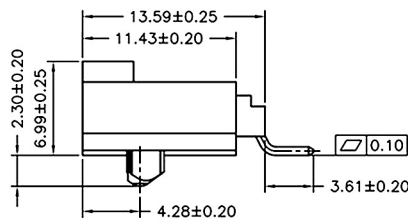
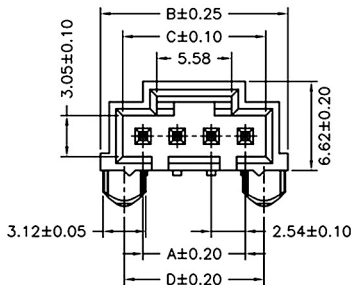


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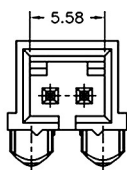
Gegenstecker / Mating connectors: 532



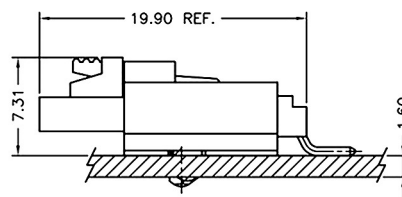
Circuit No.	Dimensions			
	A	B	C	D
02P	2.54	8.89	---	5.33
03P	5.08	11.43	8.12	7.87
04P	7.62	13.97	10.66	10.41
05P	10.16	16.51	13.20	12.95
06P	12.70	19.05	15.74	15.49
07P	15.24	21.59	18.28	18.03
08P	17.78	24.13	20.82	20.57
09P	20.32	26.67	23.36	23.11
10P	22.86	29.21	25.90	25.65
11P	25.40	31.75	28.44	28.19
12P	27.94	34.29	30.98	30.73



03P



02P



Series	Contacts*	Type	Plating	Packaging
5320	04 02-12	4 4 Stiftleiste liegend Horizontal pin header	00 00 Vergoldet Gold plated	FTR FTR

* Dies ist ein Bestellbeispiel - bitte durch Ihre Spezifikationen ersetzen.
* This is an order example - please replace by your specifications.

Lieferformen / Packaging Options:
FTR Tape & Reel mit Folien-Pads / Tape & Reel, with film tape

Informationen zum Reflow-Lötverfahren Reflow Soldering Information

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum T_{Smin}	150 °C
Temperatur Maximum T_{Smax}	200 °C
Dauer $T_{Smin} - T_{Smax}$	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature T_{Smin}	150 °C
Maximum Temperatur T_{Smax}	200 °C
Duration $T_{Smin} - T_{Smax}$	60 – 180s
Soldering Range Temperature T_L	217 °C
Duration above T_L	60 – 180s
Ramp-Up Rate $T_{Smax} - T_P$	max. 3 °C / s
Peak Temperature T_P	260±5 °C
Duration Peak Temperature	20 – 40s
Ramp-Down Rate $T_{Pmax} - T_{Smin}$	6 °C / s
Duration 25°C - Peak Temp. T_P	max. 8min

